# Accurate Evaluation of Inversion-Layer Mobility and Experimental Extraction of Local Strain Effect in sub-µm Si MOSFETs

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## 1. Introduction

Accurate evaluation of inversion-layer mobility in short channel MOSFETs has been a major concern, not only from the viewpoints of device physics and modeling, but also for the purpose of characterizing strained channel devices. Although there are a few reports on the mobility extraction in the sub-100 nm regime [1,2], the measurement method is not sufficiently reliable yet, in terms of the physical understanding of carrier transport in small devices.

This paper proposes an accurate and reliable method for the mobility extraction in short channel MOSFETs, which is based on the split-CV measurement [3]. In addition, our method is applied to a local strained channel MOSFET with a capping stressor, which shows a significant mobility enhancement with decreasing the gate length  $L_{\rm g}$ .

# 2. Mobility Extraction Method

The devices used in this measurement were simple *n*-MOSFETs without any special processes affecting the mobility. The oxide thickness  $T_{ox}$  was 5 nm and the substrate impurity concentration  $N_{\rm sub}$  was  $10^{15}$  cm<sup>-3</sup>

The proposed method, based on the split-CV measurement, is summarized in Fig.1. It was confirmed that the reduction of channel carrier density  $N_{\rm s}$  near the drain is almost negligible, even at  $L_g=1 \mu m$ .

There are three main difficulties in the mobility measurement for short channel MOSFETs. As shown in Fig.2, the value of total capacitance becomes very small, which makes it difficult to conduct an accurate CV measurement. The small total capacitance also indicates that the influence of parasitic capacitance becomes relatively significant, because the parasitic capacitance is not scaled with  $L_{g}$ . Moreover, the effective channel length  $L_{\rm eff}$  has to be determined correctly, because  $L_{\rm eff}$  can no longer be approximated as  $L_{\rm g}$ . For the accurate measurement, therefore, it is necessary to consider (i) the accuracy of CV measurement, (ii) the influence of parasitic capacitance and (iii) the determination of effective channel length.

## (i) Accuracy of CV Measurement

Since the measured gate-to-channel capacitance  $C_{gc}$  is proportional to  $L_{\rm g} \ge W_{\rm g}$ , a long channel width  $W_{\rm g}$  of 100 $\mu$ m was used in the present study. Furthermore, the influence of series resistance in short channel MOSFETs is so negligible that the measurement frequency as high as 1 MHz can be employed, which improves the accuracy in the  $C_{\rm gc}$ - $V_{\rm g}$ measurement <sup>[4]</sup>. Consequently, the accurate  $C_{gc}$  curve on the order of sub-pF was obtained, even at  $L_g=1 \mu m$  (Fig.3). (ii) Influence of Parasitic Capacitance

As shown in Fig.4, the normalized  $C_{gc}$  curve at  $L_g=1 \mu m$ agrees well with those at  $L_g=10 \ \mu m$  and 100  $\mu m$ , suggesting that the influence of parasitic capacitance can be still neglected, even at  $L_g=1 \mu m$ .

(iii) Determination of Effective Channel Length

Effective channel length is defined as  $L_{\rm eff} = L_{\rm g} - \Delta L_{\rm g}$ ,

where  $\Delta L_g$  is a channel length reduction. As is widely accepted,  $\Delta L_g$  is no longer negligible in short channel MOS-FETs. In the present study, Leff was simply determined from the  $1/I_d$  -  $L_g$  plots in the long channel regime ( $L_g$ =7-10 µm), as shown in Fig.5.

#### 3. Result and Discussion

Figure 6 shows that the determination of  $L_{\rm eff}$  can strongly affect the mobility extraction in the short channel regime, and that the extracted mobility as a function of effective normal field  $E_{\rm eff}$  is on the same curve, independent of  $L_{\rm g}$ , as a consequence of using correct  $L_{\text{eff}}$  (Fig.6 (b)). This result is reasonable under the framework of universal mobility, indicating that our measurement method is accurate and reliable

The applicability of our method to the sub-µm device is briefly discussed. We think that the determination of  $L_{\rm eff}$ will be more critical and influential to the mobility extraction, rather than the difficulties concerning the  $C_{gc}$ - $V_g$ measurement. In the present study, very simple method for determining Leff was employed. When more advanced techniques such as the shift-and-ratio method <sup>[5,6]</sup>, which can also incorporate the influence of parasitic resistance, are used, our measurement method will be available for deep sub-µm MOSFETs.

## 4. Experimental Extraction of Local Strain Effect

The proposed method was applied to *p*-MOSFETs with a compressive capping layer (Fig.7). As shown in Fig.8, mobility enhancement becomes significant with decreasing  $L_{g}$ . This is the first observation of local strain effect in terms of  $L_{\rm g}$  dependence of effective mobility. It is also noted that hole mobility is uniformly enhanced in the entire  $E_{\rm eff}$  region. Similar behaviors have been observed in the SiGe S/D and the mechanical bending experiments<sup>[7,8]</sup>, though the measurement method was not disclosed in the case of the former experiment. A quantitative agreement with the transconductance  $G_{\rm m}$  enhancement (Fig.9) suggests that our mobility results are reasonable.

## 5. Conclusion

We proposed an accurate and reliable measurement method for the mobility extraction down to the sub-µm region, as a consequence of correctly determining effective channel length. Furthermore, the direct experimental evidence of mobility enhancement was obtained in a local strained channel device by means of our method. In conclusion, our method will be a useful tool for characterizing short channel as well as strained channel MOSFETs.

# References

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